



DMS2220LFDB

P-CHANNEL ENHANCEMENT MODE MOSFET WITH INTEGRATED SBR SUPER BARRIER RECTIFIER

Features

- Low On-Resistance
 - $95m\Omega$ @VGS = -4.5V
 - 120mΩ @Vgs = -2.5V
 - 86mΩ (Typ) @VGS = -1.8V
- Low Gate Threshold Voltage, -1.3V Max
- Fast Switching Speed
- Low Input/Output Leakage
- Incorporates Low V_F Super Barrier Rectifier (SBR[®])
- Low Profile, 0.5mm Max Height
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part.
 A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

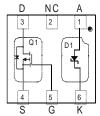
Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.0065 grams (Approximate)

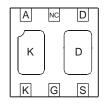
U-DFN2020-6 (Type B)



Bottom View



Top View Internal Schematic



Bottom View Pin Configuration

Ordering Information (Note 4)

Part Number	Case	Packaging
DMS2220LFDB-7	U-DFN2020-6 (Type B)	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



Marking Information

Site 1



ME = Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September) Dot Denotes Pin 1

Date Code Key

Year	2008		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	V		Н	- 1	J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



ME= Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2008	•••	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	8		0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	T	U	V	W	X	Y	Z



Maximum Ratings – TOTAL DEVICE (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	1.4	W
Thermal Resistance, Junction to Ambient	Reja	89	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Maximum Ratings - P-CHANNEL MOSFET - Q1 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	VDSS	-20	V
Gate-Source Voltage	Vgss	±12	V
Drain Current (Note 5)	I _D	-3.5	А
Pulsed Drain Current (Note 6)	IDM	-12	А

Maximum Ratings - SBR - D1 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm Vrwm Vr	20	٧
RMS Reverse Voltage	VR(RMS)	14	V
Average Rectified Output Current	lo	1	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	IFSM	3	А

Electrical Characteristics - P-CHANNEL MOSFET - Q1 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 7)	•				•			
Drain-Source Breakdown Voltage	BVDSS	-20	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$		
Zero Gate Voltage Drain Current	IDSS	_	_	-1	μΑ	V _{DS} = -20V, V _{GS} = 0V		
Gate-Source Leakage	lgss		_	±100 ±800	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$ $V_{GS} = \pm 12V$, $V_{DS} = 0V$		
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage	Vgs(th)	-0.45	1	-1.3	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$		
		_	60	95		$V_{GS} = -4.5V$, $I_{D} = -2.8A$		
Static Drain-Source On-Resistance	R _{DS(ON)}	_	74	120	mΩ	Vgs = -2.5V, ID = -2.0A		
		_	86	_		Vgs = -1.8V, ID = -1.0A		
Forward Transfer Admittance	Y _{fs}	_	8	_	S	V _{DS} = -5V, I _D = -2.8A		
Diode Forward Voltage (Note 7)	V _{SD}	_	-0.7	-1.2	V	V _{GS} = 0V, I _S = -1.6A		
DYNAMIC CHARACTERISTICS	0 \ /							
Input Capacitance	C _{iss}	_	632	_	pF	V 40V V 0V		
Output Capacitance	Coss	_	65	_	pF	V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz		
Reverse Transfer Capacitance	Crss	_	54	_	pF	1 = 1.0IVII IZ		

Electrical Characteristics - SBR - D1 (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V(BR)R	20	1		V	IR = 1mA
Forward Voltage	VF	11	11	0.45 0.52	V	IF = 0.5A IF = 1.0A
Reverse Current (Note 7)	IR	_	_	100	μΑ	VR = 20V

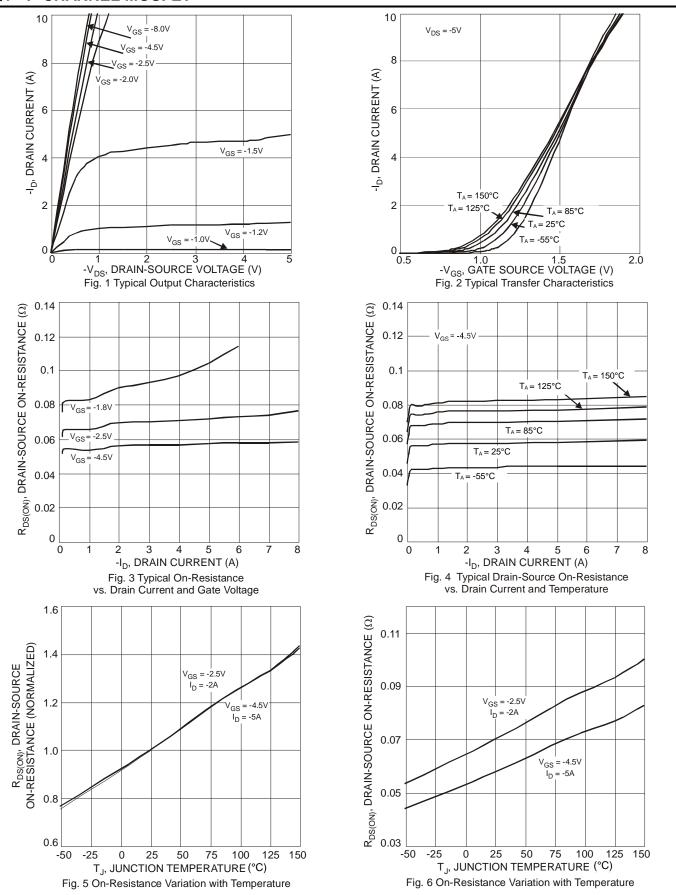
Notes: 5. Device mounted on FR-4 PCB, on minimum recommended, 2oz Copper pad layout.

^{6.} Repetitive rating, pulse width limited by junction temperature.

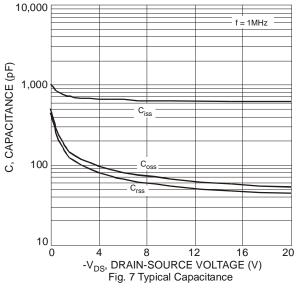
^{7.} Short duration pulse test used to minimize self-heating effect.

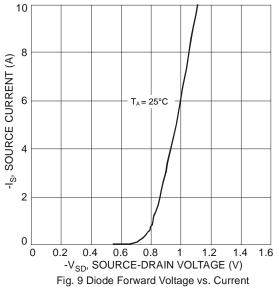


Q1 - P-CHANNEL MOSFET









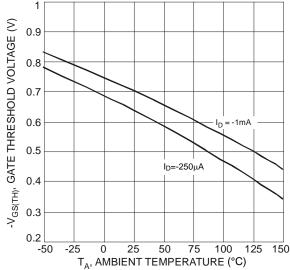


Fig. 8 Gate Threshold Variation vs. Ambient Temperature

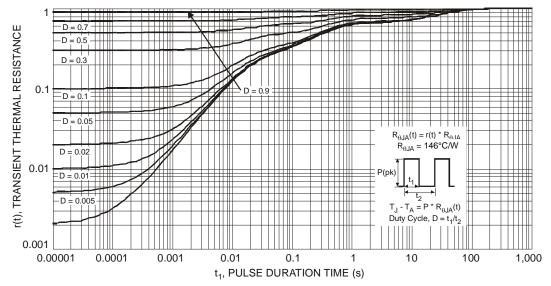
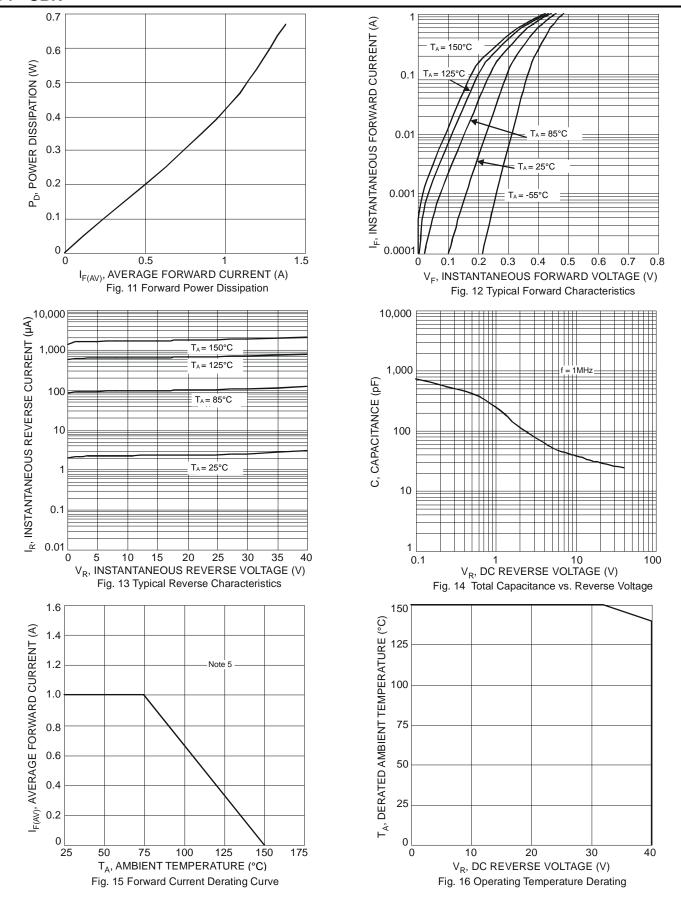


Fig. 10 Transient Thermal Response



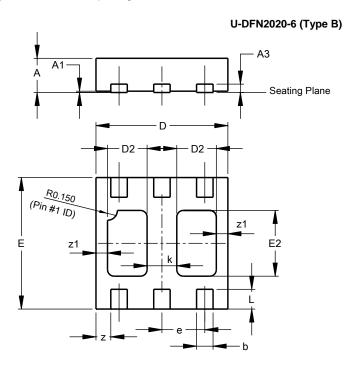
D1 - SBR





Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

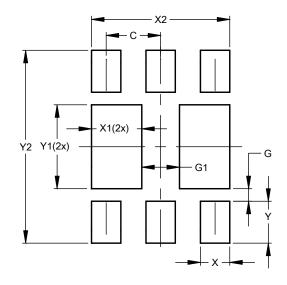


	U-DFN	2020-6							
	Type B								
Dim	Min	Min Max							
Α	0.545	0.605	0.575						
A1	0.00	0.05	0.02						
A3	-	-	0.13						
b	0.20	0.30	0.25						
D	1.95	2.075	2.00						
D2	0.50	0.70	0.60						
е	-	-	0.65						
E	1.95	2.075	2.00						
E2	0.90	1.10	1.00						
k	-	-	0.45						
L	0.25	0.35	0.30						
Z	-	-	0.225						
z 1	-	-	0.175						
All	Dimens	ions in	mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type B)



Dimensions	Value
Dillicitations	(in mm)
С	0.650
G	0.150
G1	0.450
Х	0.350
X1	0.600
X2	1.650
Y	0.500
Y1	1.000
Y2	2.300



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